



PK636 (v1.0) January 21, 2014

100% Material Declaration Data Sheet for 7 Series CLG485 Package

Average Weight: 1.0975g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.023735	2.163
	Silicon	7440-21-3	100.00		0.023735	
Die Attach Epoxy					0.007472	0.681
	Silver	7440-22-4	77.50		0.005791	
	Bismaleimide monomer	Trade Secret	15.00		0.001121	
	Acrylate monomer	Trade Secret	7.50		0.000560	
Mold Compound					0.479116	43.655
	Epoxy Resin	Trade Secret	7.50		0.035934	
	Phenol Resin A	9003-35-4	3.00		0.014374	
	Phenol Resin B	Trade Secret	3.00		0.014374	
	Silica (Amorphous) A	60676-86-0	67.95		0.325559	
	Silica (Amorphous) B	7631-86-9	15.00		0.071867	
	Metal Hydroxide	Trade Secret	3.00		0.014374	
	Carbon Black	1333-86-4	0.55		0.002635	
Copper Wire					0.006404	0.584
	Copper	7440-50-8	98.25		0.006292	
	Palladium	7440-05-3	1.75		0.000112	
Solder Ball					0.233980	21.319
	Tin	7440-31-5	96.50		0.225791	
	Silver	7440-22-4	3.00		0.007019	
	Copper	7440-50-8	0.50		0.001170	
Substrate					0.346793	31.598
	Gold	7440-57-5	0.21		0.000738	
	Nickel	7440-02-0	1.96		0.006809	
	Copper Foil	7440-50-8	18.76		0.065043	
	Copper Plating	7440-50-8	27.06		0.093831	
	Fiber Glass	65997-17-3	12.72		0.044118	
	Non Halogen Fire Retardant	Trade Secret	0.01		0.000035	
	BT Core	105391-33-1 / 25722-66-1 / 9003-36-5 / 21645-51-2	32.89		0.114054	
Solder Mask	34590-94-8 / 7727-43-7	6.39		0.022165		

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/21/2014	1.0	Xilinx Initial Release

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